

NEW!

THE NEW STANDARD IN METAL STENCIL UNDERSIDE CLEANING

Proposing a brand-new shopfloor environment, aiming for a complete departure from IPA. Transforming the bottom-side cleaning process of solder paste printing.



ZERO FLASH POINT!



SAWA TRADING INC.





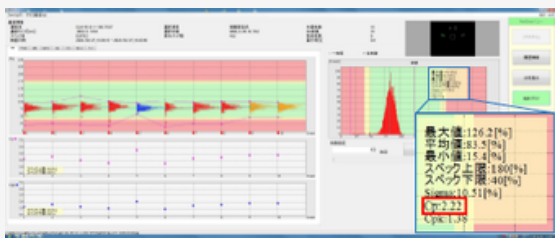
3 Surprising Features

1 Completely Non-Flammable (Zero Flash Point)

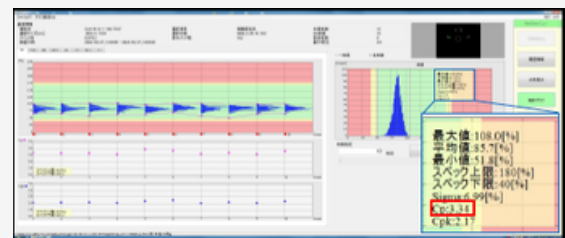
Easy to introduce into factory environments with no flash point. Designed with low-VOC specifications that comply with China's GB standards, ensuring minimal environmental impact.

2 Outstanding Wipe-Off Performance & Major Cp Improvement

Free from surfactants found in conventional aqueous cleaners, leaving zero cleaning residue. It stabilizes solder quality while achieving stable release performance through our unique mechanism, dramatically improving Cp values.



IPA 2.22



UB-0701U 3.34

3 Mechanism to Maximize Printer Performance

Designed to fully leverage the cleaning mechanism of printing machines. Instead of conventional "spread and wipe," it delivers powerful cleaning through a brand-new approach of "wet and wipe."

